

Vishay Siliconix

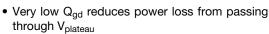
N-Channel 100 V (D-S) MOSFET



PRODUCT SUMMARY	
V _{DS} (V)	100
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.00288
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 7.5 \text{ V}$	0.00348
Q _g typ. (nC)	142.4
I _D (A)	150 ^d
Configuration	Single

FEATURES

- TrenchFET® power MOSFET
- Maximum 175 °C junction temperature

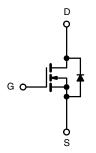




- 100 % R_a and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Power supply
 - Secondary synchronous rectification
- DC/DC converter
- Power tools
- · Motor drive switch
- DC/AC inverter
- · Battery management
- OR-ing / e-fuse



N-Channel MOSFET

ORDERING INFORMATION	
Package	TO-263
Lead (Pb)-free and halogen-free	SUM70030E-GE3

ABSOLUTE MAXIMUM RATING	3S (T _C = 25 °C, unle	ss otherwise note	d)	
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V _{DS}	100	V
Gate-source voltage		V _{GS}	± 20	v
Continuous drain surrent (T. 150 °C)	T _C = 25 °C	,	150 ^d	
Continuous drain current (T _J = 150 °C)	T _C = 70 °C	l _D	150 ^d	d
Pulsed drain current (t = 100 μs)		I _{DM}	500	— A
Avalanche current		I _{AS}	60	
Single avalanche energy ^a	L = 0.1 mH	E _{AS}	180	mJ
Martin and a district of the 3	T _C = 25 °C	Б	375 b	W
Maximum power dissipation ^a	T _C = 125 °C	P _D	125 ^b	vv
Operating junction and storage temperature	e range	T _J , T _{stg}	-55 to +175	°C

THERMAL RESISTANCE RATINGS			
PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-ambient (PCB mount) ^c	R _{thJA}	40	°C/W
Junction-to-case (drain)	R _{thJC}	0.4	J 5/VV

Notes

- a. Duty cycle \leq 1 %
- b. See SOA curve for voltage derating
- c. When mounted on 1" square PCB (FR4 material)
- d. Package limited



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100	-	-	V	
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2	-	4	V	
Gate-body leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 250	nA	
		V _{DS} = 100 V, V _{GS} = 0 V	-	-	1		
Zero gate voltage drain current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C	-	-	150	μA	
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 175 °C	-	-	5	mA	
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	120	-	-	Α	
Dusing assumes are state unsinternal 2		V _{GS} = 10 V, I _D = 30 A	-	0.00240	0.00288		
Drain-source on-state resistance a	R _{DS(on)}	V _{GS} = 7.5 V, I _D = 20 A	-	0.00290	0.00348	Ω	
Forward transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A	-	110	-	S	
Dynamic ^b							
Input capacitance	C _{iss}		-	10 870	-		
Output capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 50 \text{ V}, f = 1 \text{ MHz}$	-	820	-	рF	
Reverse transfer capacitance	C _{rss}		-	40	-		
Total gate charge ^c	Qg		-	142.4	214		
Gate-source charge ^c	Q _{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	46.8	-		
Gate-drain charge ^c	Q _{gd}		-	18.5	-	nC	
Output charge	Q _{oss}	V _{DS} = 50 V, V _{GS} = 0 V	-	138	207		
Gate resistance	R _g	f = 1 MHz	0.34	1.7	3.4	Ω	
Turn-on delay time ^c	t _{d(on)}		-	30	60		
Rise time ^c	t _r	$V_{DD} = 50 \text{ V}, R_L = 3 \Omega$	-	13	26		
Turn-off delay time ^c	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	50	100	ns	
Fall time ^c	t _f		-	15	30		
Drain-Source Body Diode Ratings	and Characte	ristics ^b (T _C = 25 °C)		•	•		
Pulsed current (t = 100 μs)	I _{SM}		-	-	250	Α	
Forward voltage ^a	V _{SD}	I _F = 10 A, V _{GS} = 0 V	-	0.8	1.5	V	
Reverse recovery time	t _{rr}		-	76	150	ns	
Peak reverse recovery charge	I _{RM(REC)}		-	4.6	5.6	Α	
Reverse recovery charge	Q _{rr}	$I_F = 34 \text{ A}$, di/dt = 100 A/ μ s	-	0.205	0.24	μC	
Reverse recovery fall time	ta		-	52	-	no	
Reverse recovery rise time	t _b		-	24	-	ns	

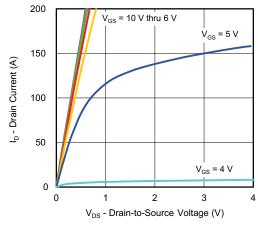
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

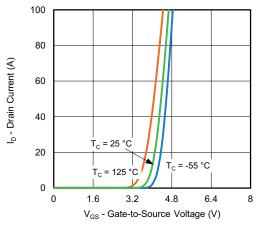
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



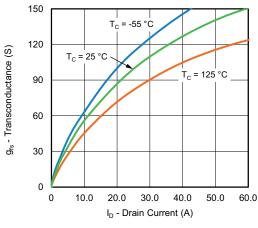
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



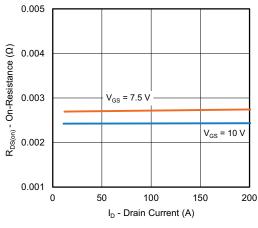
Output Characteristics



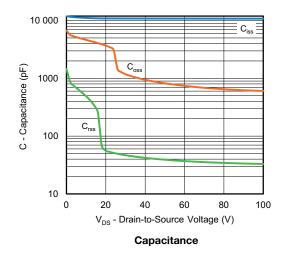
Transfer Characteristics

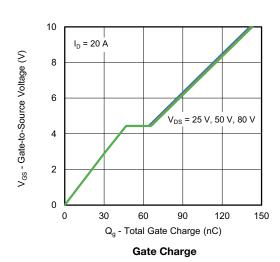


Transconductance



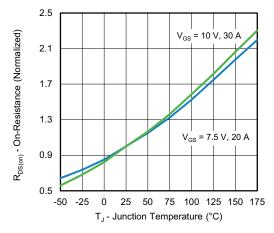
On-Resistance vs. Drain Current



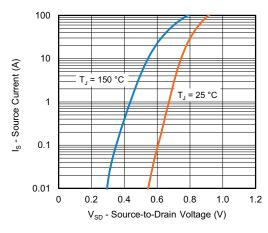




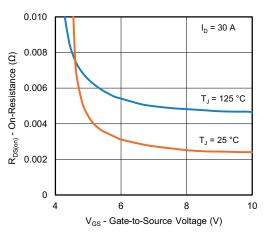
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



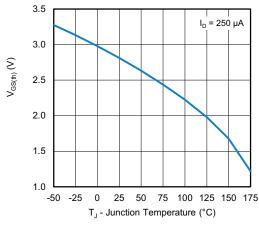
On-Resistance vs. Junction Temperature



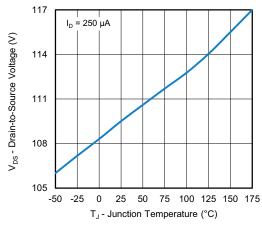
Source Drain Diode Forward Voltage



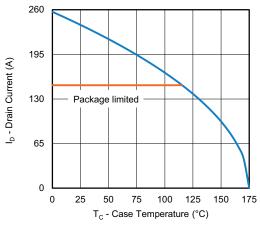
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



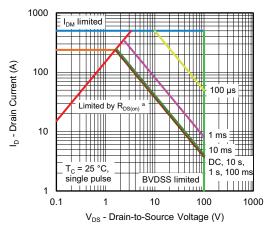
Drain Source Breakdown vs. Junction Temperature



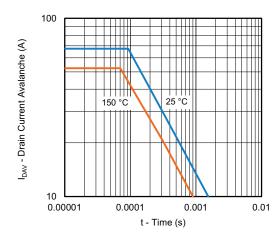
Current De-rating



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



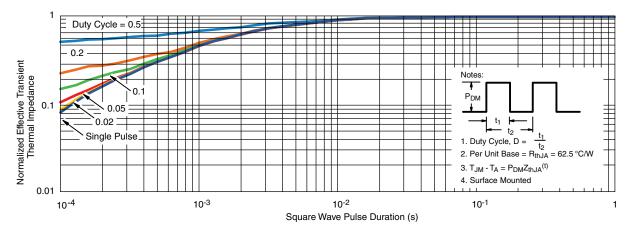




Single Pulse Avalanche Current Capability vs. Time

Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction to Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual pplication parameters and operating conditions

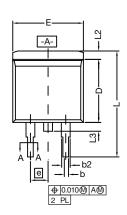
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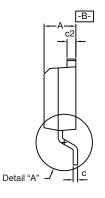
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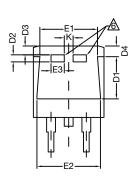


TO-263 (D²PAK): 3-LEAD

VERSION 1: FACILITY CODE = T

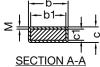








DETAIL A (ROTATED 90°)



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SF	CTION	1	1

Notes

- 1. Plane B includes maximum features of heat sink tab and plastic.
- 2. No more than 25 % of L1 can fall above seating plane by max. 8 mils.
- 3. Pin-to-pin coplanarity max. 4 mils.
- 4. *: Thin lead is for SUB, SYB. Thick lead is for SUM, SYM, SQM.
- 5. Use inches as the primary measurement.

6. This feature is for thick lead.

		INC	HES	MILLIN	METERS
	DIM.	MIN.	MAX.	MIN.	MAX.
A		0.160	0.190	4.064	4.826
b		0.020	0.039	0.508	0.990
b1		0.020	0.035	0.508	0.889
	b2	0.045	0.055	1.143	1.397
c*	Thin lead	0.013	0.018	0.330	0.457
١	Thick lead	0.023	0.028	0.584	0.711
c1	Thin lead	0.013	0.017	0.330	0.431
Ü	Thick lead	0.023	0.027	0.584	0.685
	c2	0.045	0.055	1.143	1.397
	D	0.340	0.380	8.636	9.652
	D1	0.220	0.240	5.588	6.096
	D2	0.038	0.042	0.965	1.067
	D3	0.045	0.055	1.143	1.397
	D4	0.044	0.052	1.118	1.321
	E	0.380	0.410	9.652	10.414
	E1	0.245	-	6.223	-
	E2	0.355	0.375	9.017	9.525
	E3	0.072	0.078	1.829	1.981
	е	0.100 BSC		2.54	BSC
	K 0.045 0.055 1.143		1.397		
	L	0.575	0.625	14.605	15.875
	L1	0.090	0.110	2.286	2.794
	L2	0.040	0.055	1.016	1.397
	L3	0.050	0.070	1.270	1.778
	L4	0.010	BSC	0.254	BSC
	М	-	0.002	-	0.050

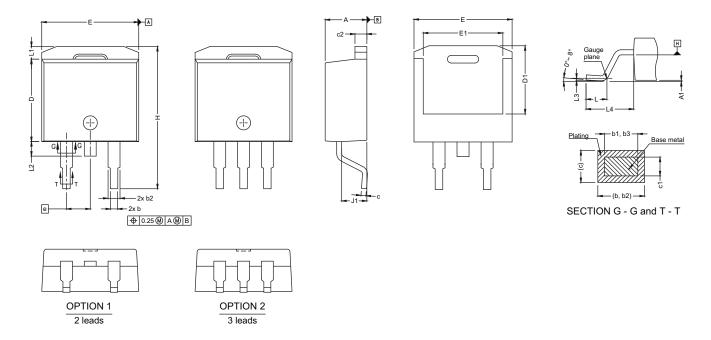
Revison: 28-Oct-2024 Document Number: 71198



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VERSION 2: FACILITY CODE = N



DIM.	MIN.	MAX.
A	4.36	4.56
A1	0	0.25
b	0.70	0.90
b1	0.51	0.89
b2	1.20	1.46
b3	1.17	1.37
С	0.38	0.694
c1	0.38	0.534
c2	1.19	1.34
D	8.60	9.00
D1	6.9	7.5
E	10.15	10.55
E1	8.1	8.7
е	2.54	BSC
Н	15.0	15.6
L	1.9	2.5
L1	-	1.65
L2	-	1.78
L3	0.25	5 typ.
L4	4.78	5.28
J1	2.56	2.96

DWG: 5843





RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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